

IFN363 N-Channel JFET

Features

- InterFET [N0450H Geometry](#)
- Low Noise: 1.1 nV/√Hz Typical
- High Gain: 60mS Typical
- RoHS Compliant
- SMT, TH, and Bare Die Package options.

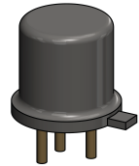
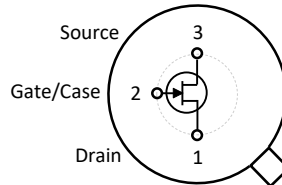
Applications

- Low-Noise Audio Amplifier
- Replacement for Japanese 2SK363

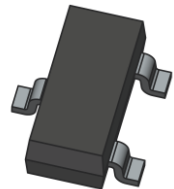
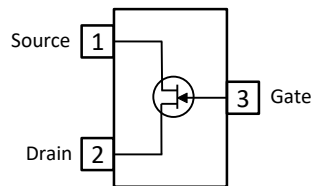
Description

The -40V InterFET IFN363 is a low noise high gain replacement for the Japanese 2SK363 JFET. Gate leakages are typically less than 50pA at room temperatures. The TO-18 package is hermetically sealed and suitable for military applications.

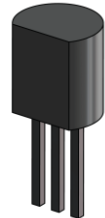
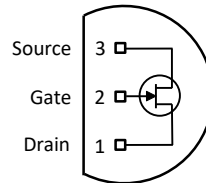
TO-18 Bottom View



SOT23 Top View



TO-92 Bottom View



Product Summary

Parameters		IFN363 Min	Unit
BV _{GSS}	Gate to Source Breakdown Voltage	-40	V
I _{DSS}	Drain to Source Saturation Current	5	mA
V _{GS(off)}	Gate to Source Cutoff Voltage	-0.3	V
G _{FS}	Forward Transconductance	60 (typ)	mS

Ordering Information

Part Number	Description	Case	Packaging
IFN363	Through-Hole	TO-18	Bulk
PN363	Through-Hole	TO-92	Bulk
SMP363	Surface Mount	SOT23	Bulk
SMP363TR	7" Tape and Reel: Max 3,000 Pieces 13" Tape and Reel: Max 9,000 Pieces	SOT23	Minimum 1,000 Pieces Tape and Reel
IFN363COT	Chip Orientated Tray (COT Waffle Pack)	COT	400/Waffle Pack
IFN363CFT	Chip Face-up Tray (CFT Waffle Pack)	CFT	400/Waffle Pack



Disclaimer: It is the Buyers responsibility for designing, validating and testing the end application under all field use cases and extreme use conditions. Guaranteeing the application meets required standards, regulatory compliance, and all safety and security requirements is the responsibility of the Buyer. These resources are subject to change without notice.

Electrical Characteristics

Maximum Ratings (@ $T_A = 25^\circ\text{C}$, Unless otherwise specified)

Parameters	Value	Unit
V_{RGS} Reverse Gate Source and Gate Drain Voltage	-40	V
I_{FG} Continuous Forward Gate Current	10	mA
P_D Continuous Device Power Dissipation	300	mW
P Power Derating	2.8	mW/ $^\circ\text{C}$
T_J Operating Junction Temperature	-55 to 125	$^\circ\text{C}$
T_{STG} Storage Temperature	-65 to 150	$^\circ\text{C}$

Static Characteristics (@ $T_A = 25^\circ\text{C}$, Unless otherwise specified)

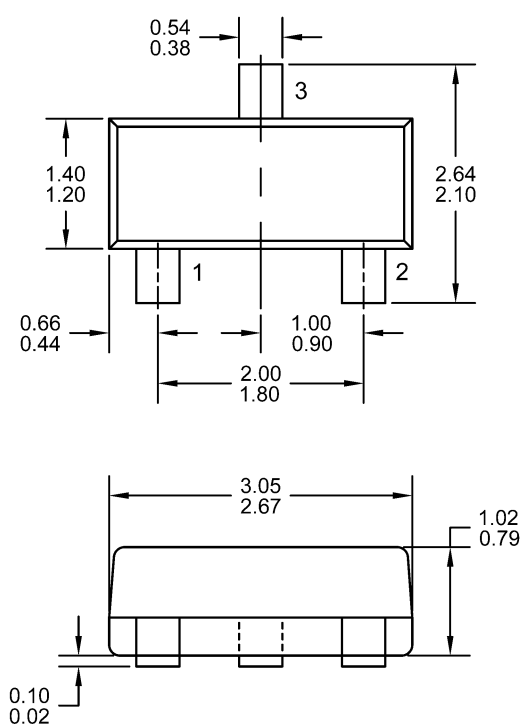
Parameters	Conditions	IFN363		Unit
		Min	Max	
$V_{(BR)GSS}$ Gate to Source Breakdown Voltage	$V_{DS} = 0V, I_G = -1\mu A$	-40		V
I_{GSS} Gate to Source Reverse Current	$V_{GS} = -30V, V_{DS} = 0V$		1	nA
$V_{GS(OFF)}$ Gate to Source Cutoff Voltage	$V_{DS} = -10V, I_D = 100nA$	-0.3	-1.2	V
I_{DSS} Drain to Source Saturation Current	$V_{GS} = 0V, V_{DS} = -10V$ (Pulsed)	5	30	mA

Dynamic Characteristics (@ $T_A = 25^\circ\text{C}$, Unless otherwise specified)

Parameters	Conditions	IFN363	Unit
		Typ	
G_{FS} Forward Transconductance	$V_{DS} = -10V, V_{GS} = 0V, f = 1kHz$	60	mS
C_{iss} Input Capacitance	$V_{DS} = -10V, V_{GS} = 0V, f = 1MHz$	75	pF
C_{rss} Reverse Transfer Capacitance	$V_{DS} = 10V, V_{GS} = 0V, f = 1MHz$	15	pF

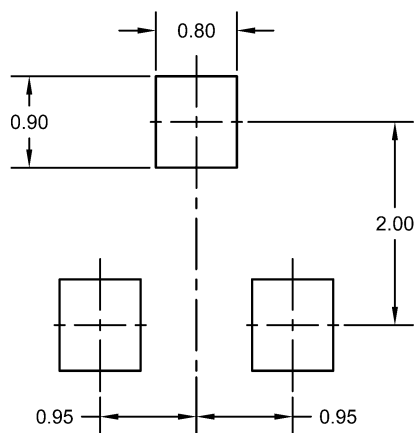
SOT23 (TO-236AB) Mechanical and Layout Data

Package Outline Data



1. All linear dimensions are in millimeters.
2. Package weight approximately 0.12 grams
3. Molded plastic case UL 94V-0 rated
4. For Tape and Reel specifications refer to InterFET CTC-021 Tape and Reel Specification, Document number: IF39002
5. Bulk product is shipped in standard ESD shipping material
6. Refer to JEDEC standards for additional information.

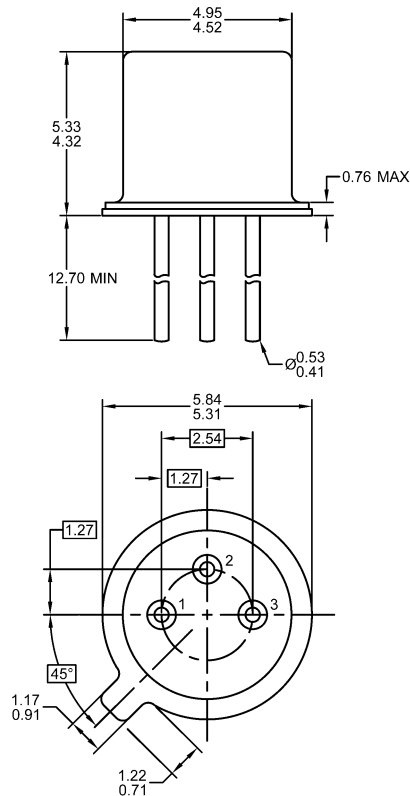
Suggested Pad Layout



1. All linear dimensions are in millimeters.
2. The suggested land pattern dimensions have been provided for reference only. A more robust pattern may be desired for wave soldering.

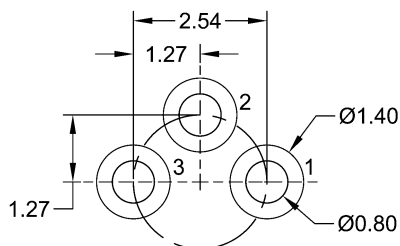
TO-18 Mechanical and Layout Data

Package Outline Data



1. All linear dimensions are in millimeters.
2. Package weight approximately 0.29 grams
3. Bulk product is shipped in standard ESD shipping material
4. Refer to JEDEC standards for additional information.

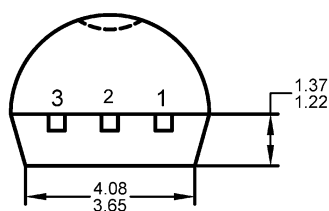
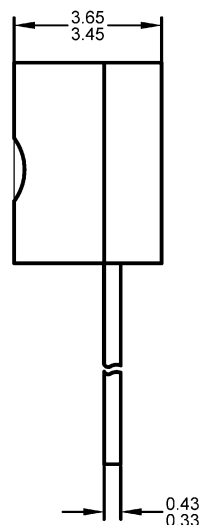
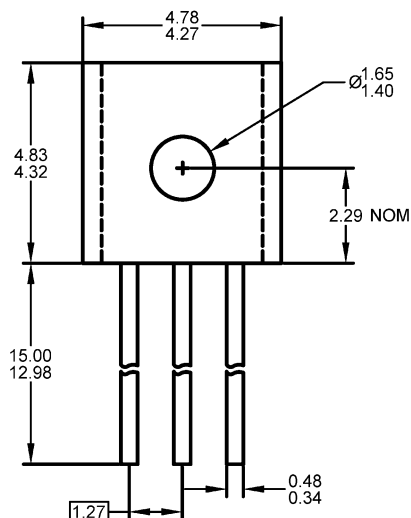
Suggested Through-Hole Layout



1. All linear dimensions are in millimeters.
2. The suggested land pattern dimensions have been provided as a straight lead reference only. A more robust pattern may be desired for wave soldering and/or bent lead configurations.

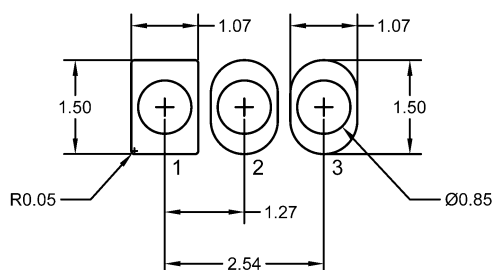
TO-92 Mechanical and Layout Data

Package Outline Data



1. All linear dimensions are in millimeters.
2. Package weight approximately 0.19 grams
3. Molded plastic case UL 94V-0 rated
4. Bulk product is shipped in standard ESD shipping material
5. Refer to JEDEC standards for additional information.

Suggested Through-Hole Layout



1. All linear dimensions are in millimeters.
2. The suggested land pattern dimensions have been provided as a straight lead reference only. A more robust pattern may be desired for wave soldering and/or bent lead configurations.

Mouser Electronics

Authorized Distributor

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